



Si Technology Leader



- ☐ Advanced Process & Module Development (DRAM, Flash, Logic, etc.)
 - Photolithography (e-beam, EUV, OPC/RET, Photo Resist Materials), Dry Etch, Cleaning & CMP, Diffusion, Ion Implantation, Metallization, Metrology & Inspection, etc.
 - Device Isolation, Transistor, Capacitor, Dielectric
 - High-K/Metal Gate, SD2/SDN Gate Dielectric
 - Low-K, Interconnect, etc.
 - OPC : Optical Proximity Correction (Comput. Litho), MPC : Mask Process Correction
 - ☐ FEOL/BEOL Process Integration (DRAM / Flash / Logic, etc.)
 - ☐ New Memory : PRAM, STT-MRAM, ReRAM, etc.
 - ☐ TCAD/ECAD
 - Process & Device/Material Modeling, Circuit Compact/Reliability Modeling
 - Circuit Simulator Development
 - System-Level Modeling / Simulation, Virtual Platform, HW / SW Co-Design
 - Simics/CoWare/SOC Designer Use Memory Controller/Memory Architecture/SSD Research Experience
 - ☐ Advanced CMOS Image Sensor (CS) Development
 - Pixel Design, Image Signal Processing, Mixed IC Design, Analog/Digital Design
 - CS Process Development
 - ☐ Package Development
 - Wire Bonding & Flip Chip Package / Wafer Level Package (WLP/TSV)
 - Thinning PKG/Chip Warpage Control, Signal/Power/Thermal
 - Material Development & Failure Analysis
 - ☐ Material Development & Environment Contamination Control
 - Material(Wafer, PR, Gas, Chemical, Thin Film) Development
 - FAB Environment Contamination Monitoring & Control
 - Material & Environment Failure Analysis and Quality Guarantee
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